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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 350K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA, FC (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxfb3h4f40i5n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Advantage	Supporting Feature
Lowest system cost	 Requires as few as four power supplies to operate Available in thermal composite flip chip ball-grid array (BGA) packaging Includes innovative features such as Configuration via Protocol (CvP), partial reconfiguration, and design security

Summary of Arria V Features

Table 2: Summary of Features for Arria V Devices

Feature	Description
Technology	 TSMC's 28-nm process technology: Arria V GX, GT, SX, and ST—28-nm low power (28LP) process Arria V GZ—28-nm high performance (28HP) process Lowest static power in its class (less than 1.2 W for 500K logic elements (LEs) at 85°C junction under typical conditions) 0.85 V, 1.1 V, or 1.15 V core nominal voltage
Packaging	 Thermal composite flip chip BGA packaging Multiple device densities with identical package footprints for seamless migration between different device densities Leaded⁽¹⁾, lead-free (Pb-free), and RoHS-compliant options
High-performance FPGA fabric	 Enhanced 8-input ALM with four registers Improved routing architecture to reduce congestion and improve compilation time
Internal memory blocks	 M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) (Arria V GX, GT, SX, and ST devices only) M20K—20-Kb memory blocks with hard ECC (Arria V GZ devices only) Memory logic array block (MLAB)-640-bit distributed LUTRAM where you can use up to 50% of the ALMs as MLAB memory

Send Feedback

 $^{^{(1)}}$ Contact Altera for availability.

Feature		Description					
Embedded Hard IP blocks	Memory controller (Arria V GX, GT, SX, and ST only) Embedded transceiver I/O	 Native support for up to four signal processing precision levels: Three 9 x 9, two 18 x 18, or one 27 x 27 multiplier in the same variable-precision DSP block One 36 x 36 multiplier using two variable-precision DSP blocks (Arria V GZ devices only) 64-bit accumulator and cascade for systolic finite impulse responses (FIRs) Embedded internal coefficient memory Preadder/subtractor for improved efficiency DDR3 and DDR2 Custom implementation: Arria V GX and SX devices—up to 6.5536 Gbps Arria V GT and ST devices—up to 10.3125 Gbps Arria V GZ devices—up to 12.5 Gbps PCI Express® (PCIe®) Gen2 (x1, x2, or x4) and Gen1 (x1, x2, x4, or x8) hard IP with multifunction support, endpoint, and root port PCIe Gen3 (x1, x2, x4, or x8) support (Arria V GZ only) Gbps Ethernet (GbE) and XAUI physical coding sublayer (PCS) Common Public Radio Interface (CPRI) PCS Gigabit-capable passive optical network (GPON) PCS 10-Gbps Ethernet (10GbE) PCS (Arria V GZ only) Serial RapidIO® (SRIO) PCS Interlaken PCS (Arria V GZ only) 					
Clock networks	Global, quadrant, a	to 650 MHz global clock network obal, quadrant, and peripheral clock networks ock networks that are not used can be powered down to reduce dynamic power					
Phase-locked loops (PLLs)	Precision clock syn (ZDB)Integer mode and f	esolution fractional PLLs on clock synthesis, clock delay compensation, and zero delay buffering mode and fractional mode illator ATX transmitter PLLs (Arria V GZ only)					



Feature	Description
FPGA General- purpose I/Os (GPIOs)	 1.6 Gbps LVDS receiver and transmitter 800 MHz/1.6 Gbps external memory interface On-chip termination (OCT) 3.3 V support (2)
External Memory Interface	 Memory interfaces with low latency: Hard memory controller-up to 1.066 Gbps Soft memory controller-up to 1.6 Gbps
Low-power high- speed serial interface	 600 Mbps to 12.5 Gbps integrated transceiver speed Less than 105 mW per channel at 6 Gbps, less than 165 mW per channel at 10 Gbps, and less than 170 mW per channel at 12.5 Gbps Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels Physical medium attachment (PMA) with soft PCS that supports 9.8304 Gbps CPRI (Arria V GT and ST only) PMA with hard PCS that supports up to 9.8 Gbps CPRI (Arria V GZ only) Hard PCS that supports 10GBASE-R and 10GBASE-KR (Arria V GZ only)
HPS (Arria V SX and ST devices only)	 Dual-core ARM Cortex-A9 MPCore processor—up to 1.05 GHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, serial peripheral interface (SPI), I2C interface, and up to 85 HPS GPIO interfaces System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers On-chip RAM and boot ROM HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller ARM CoreSight™ JTAG debug access port, trace port, and on-chip trace storage



 $^{^{(2)}~{\}rm Arria~V~GZ}$ devices support 3.3 V with a 3.0 V ${\rm V}_{\rm CCIO}.$

Resource		Member Code							
nesc	uice	A1	А3	A 5	A7	B1	В3	B5	В7
6 Gbps Transc		9	9	24	24	24	24	36	36
GPIO ⁽	(3)	416	416	544	544	704	704	704	704
LVD S	Transmi tter	67	67	120	120	160	160	160	160
3	Receiver	80	80	136	136	176	176	176	176
PCIe I Block	Hard IP	1	1	2	2	2	2	2	2
Hard I Contro	Memory oller	2	2	4	4	4	4	4	4

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 5: Package Plan for Arria V GX Devices

Member Code		F672 (27 mm)				F1152 (35 mm)		F1517 (40 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	
A1	336	9	416	9	_	_	_	_	
A3	336	9	416	9	_	_	_	_	
A5	336	9	384	18	544	24	_	_	
A7	336	9	384	18	544	24	_	_	
B1	_	_	384	18	544	24	704	24	
В3	_	_	384	18	544	24	704	24	
B5	_	_	_	_	544	24	704	36	
В7	_	_	_	_	544	24	704	36	

Arria V GT

This section provides the available options, maximum resource counts, and package plan for the Arria V GT devices.



⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus[®] Prime software, the number of user I/Os includes transceiver I/Os.

Resource		Member Code						
Neso	ui ce	C 3	C 7	D3	D7			
Transceiver	6 Gbps ⁽⁴⁾	3 (9)	6 (24)	6 (24)	6 (36)			
Transcerver	10 Gbps ⁽⁵⁾	4	12	12	20			
GPIO ⁽⁶⁾	GPIO ⁽⁶⁾		544	704	704			
LVDS	Transmitter	68	120	160	160			
LVD3	Receiver	80	136	176	176			
PCIe Hard IP	PCIe Hard IP Block		2	2	2			
Hard Memor	y Controller	2	4	4	4			

• High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

• Transceiver Architecture in Arria V Devices

Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 7: Package Plan for Arria V GT Devices

Memb		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)		F1517 (40 mm)				
er Code		ХС	VR		ХС	VR		ХС	VR		2	KCVR
	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10-Gbps
C3	336	3 (9)	4	416	3 (9)	4	_	_	_	_	_	_
C7	_	_	_	384	6 (18)	8	544	6 (24)	12	_	_	_
D3	_	_	_	384	6 (18)	8	544	6 (24)	12	704	6 (24)	12
D7	_	_	_	_	_	_	544	6 (24)	12	704	6 (36)	20

The 6-Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10-Gbps channels as three 6-Gbps channels—the total number of 6-Gbps channels are shown in brackets. For example, you can also configure the Arria V GT D7 device in the F1517 package with nine 6-Gbps



⁽⁴⁾ The 6 Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10 Gbps channels as three 6 Gbps channels-the total number of 6 Gbps channels are shown in brackets.

⁽⁵⁾ Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

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and eighteen 10-Gbps, twelve 6-Gbps and sixteen 10-Gbps, fifteen 6-Gbps and fourteen 10-Gbps, or up to thirty-six 6-Gbps with no 10-Gbps channels.

Arria V GZ

This section provides the available options, maximum resource counts, and package plan for the Arria V GZ devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

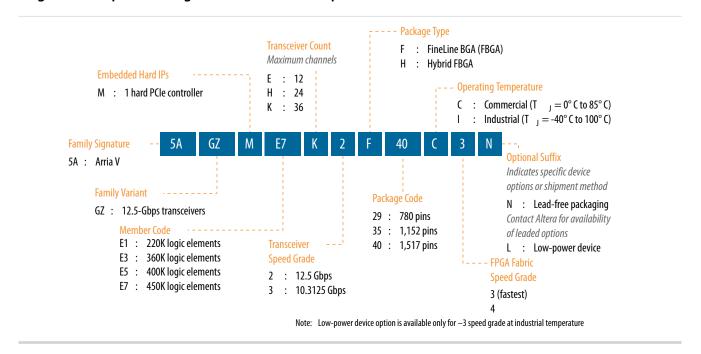
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 3: Sample Ordering Code and Available Options for Arria V GZ Devices



Maximum Resources

Table 8: Maximum Resource Counts for Arria V GZ Devices

Resource	Member Code						
nesource	E1	E 3	E 5	E 7			
Logic Elements (LE) (K)	220	360	400	450			
ALM	83,020	135,840	150,960	169,800			
Register	332,080	543,360	603,840	679,200			



Resource		Member Code						
nesc	nesource		E 3	E 5	E 7			
Memory	M20K	11,700	19,140	28,800	34,000			
(Kb)	MLAB	2,594	4,245	4,718	5,306			
Variable-pred	Variable-precision DSP Block		1,044	1,092	1,139			
18 x 18 Multi	18 x 18 Multiplier		2,088	2,184	2,278			
PLL	PLL		20	24	24			
12.5 Gbps Tr	ansceiver	24	24	36	36			
GPIO ⁽⁷⁾		414	414	674	674			
LVDS	Transmitter	99	99	166	166			
LVDS	Receiver	108	108	168	168			
PCIe Hard IF	Block	1	1	1	1			

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 9: Package Plan for Arria V GZ Devices

Member Code	H780 (33 mm)			152 mm)	F1517 (40 mm)		
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	
E1	342	12	414	24	_	_	
E3	342	12	414	24	_	_	
E5	_	_	534	24	674	36	
E7	_	_	534	24	674	36	

Arria V SX

This section provides the available options, maximum resource counts, and package plan for the Arria V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.



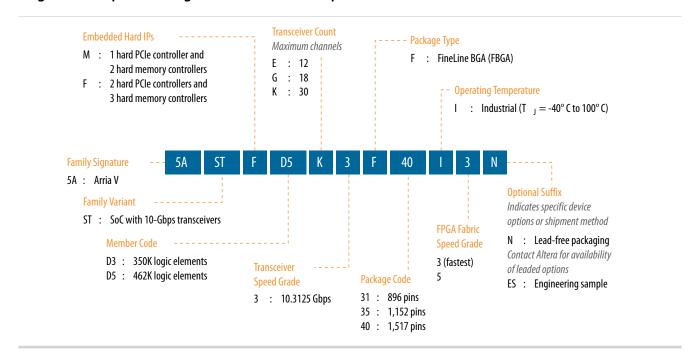
⁽⁷⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

Table 12: Maximum Resource Counts for Arria V ST Devices

Reso	LINEO	Member Code			
Reso	ource	D3	D5		
Logic Elements (LE)	(K)	350	462		
ALM		132,075	174,340		
Register		528,300	697,360		
Memory (Kb)	M10K	17,290	22,820		
Memory (Rb)	MLAB	2,014	2,658		
Variable-precision D	SP Block	809	1,090		
18 x 18 Multiplier		1,618	2,180		
FPGA PLL		14	14		
HPS PLL		3	3		
Transceiver	6-Gbps	30	30		
Transcerver	10-Gbps ⁽⁹⁾	16	16		



Poso	ource	Member Code			
neso	raice	D3	D5		
FPGA GPIO ⁽¹⁰⁾		540	540		
HPS I/O		208	208		
LVDS	Transmitter	120	120		
LVD3	Receiver	136	136		
PCIe Hard IP Block		2	2		
FPGA Hard Memory	PGA Hard Memory Controller		3		
HPS Hard Memory C	Controller	1	1		
ARM Cortex-A9 MP	Core Processor	Dual-core	Dual-core		

• High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Transceiver Architecture in Arria V Devices
 Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 13: Package Plan for Arria V ST Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Memb	F896 (31 mm)			F1152 (35 mm)			F1517 (40 mm)					
er Code	FPGA	HPS	ХС	VR	FPGA	HPS	ХС	VR	FPGA	HPS		KCVR
	GPIO I/O 6 Gbps 10 Gbps	GPIO I/O	6 Gbps	10 Gbps	GPIO	I/O	6 Gbps	10 Gbps				
D3	250	208	12	6	385	208	18	8	540	208	30	16
D5	250	208	12	6	385	208	18	8	540	208	30	16



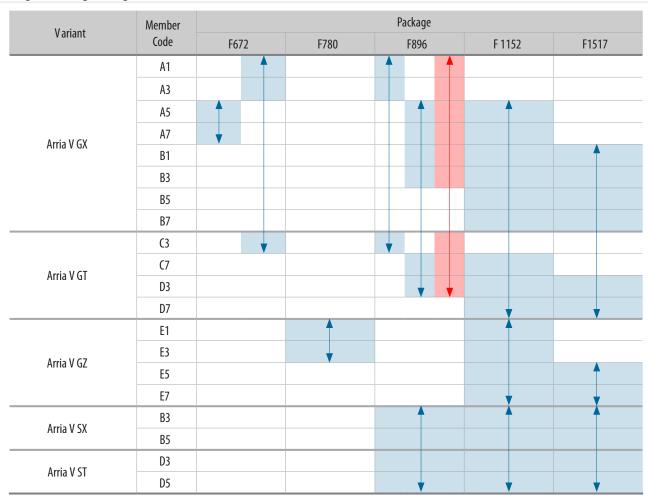
⁽⁹⁾ Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

⁽¹⁰⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

I/O Vertical Migration for Arria V Devices

Figure 6: Vertical Migration Capability Across Arria V Device Packages and Densities

The arrows indicate the vertical migration paths. Some packages have several migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 320 GPIOs, up to nine 6 Gbps transceiver channels, and up to four 10 Gbps transceiver (for Arria V GT devices). This migration path is not shown in the Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Quartus Prime software Pin Planner.

Note: Except for Arria V GX A5 and A7, and Arria V GT C7 devices, all other Arria V GX and GT devices require a specific power-up sequence. If you plan to migrate your design from Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices, your design must adhere to the same required power-up sequence.



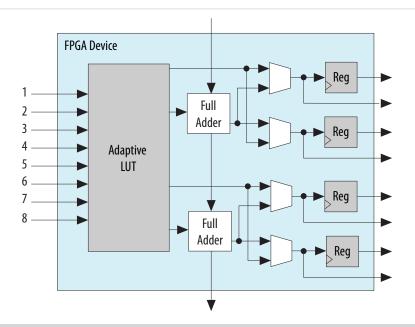
- Managing Device I/O Pins chapter, Quartus Prime Handbook Provides more information about vertical I/O migrations.
- Power Management in Arria V Devices
 Describes the power-up sequence required for Arria V GX and GT devices.

Adaptive Logic Module

Arria V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 7: ALM for Arria V Devices



You can configure up to 50% of the ALMs in the Arria V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Arria V Devices on page 20

Lists the embedded memory capacity for each device.



Variable-Precision DSP Block

Arria V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18, 27 x 27, and 36 x 36 bits natively
- A 64-bit accumulator
- Double accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Dynamic coefficients
- 18-bit internal coefficient register banks
- Enhanced independent multiplier operation
- Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Quartus Prime design software

Table 14: Variable-Precision DSP Block Configurations for Arria V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters	Two 18 x 18 with accumulate	1
Single-precision floating- point implementations	One 27 x 27	1
Very high precision fixed point implementations	One 36 x 36	2

You can configure each DSP block during compilation as independent three 9 x 9, two 18 x 18, or one 27×27 multipliers. Using two DSP block resources, you can also configure a 36×36 multiplier for high-precision applications. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.



Table 15: Number of Multipliers in Arria V Devices

The table lists the variable-precision DSP resources by bit precision for each Arria V device.

Variant	Mem Variable- Variant ber precision		Independ	ent Input and Ope	18 x 18 Multiplier	18 x 18 Multiplier Adder Summed		
Variant	Code	DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	36 x 36 Multiplier	Adder Mode	with 36 bit Input
	A1	240	720	480	240	_	240	240
	A3	396	1,188	792	396	_	396	396
	A5	600	1,800	1,200	600	_	600	600
Arria V	A7	800	2,400	1,600	800	_	800	800
GX	B1	920	2,760	1,840	920	_	920	920
	В3	1,045	3,135	2,090	1,045	_	1,045	1,045
	B5	1,092	3,276	2,184	1,092	_	1,092	1,092
	B7	1,156	3,468	2,312	1,156	_	1,156	1,156
	C3	396	1,188	792	396	_	396	396
Arria V	C7	800	2,400	1,600	800	_	800	800
GT	D3	1,045	3,135	2,090	1,045	_	1,045	1,045
	D7	1,156	3,468	2,312	1,156	_	1,156	1,156
	E1	800	2,400	1,600	800	400	800	800
Arria V	Е3	1,044	3,132	2,088	1,044	522	1,044	1,044
GZ	E5	1,092	3,276	2,184	1,092	546	1,092	1,092
	E7	1,139	3,417	2,278	1,139	569	1,139	1,139
Arria V	В3	809	2,427	1,618	809	_	809	809
SX	B5	1,090	3,270	2,180	1,090	_	1,090	1,090
Arria V	D3	809	2,427	1,618	809	_	809	809
ST	D5	1,090	3,270	2,180	1,090	_	1,090	1,090

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



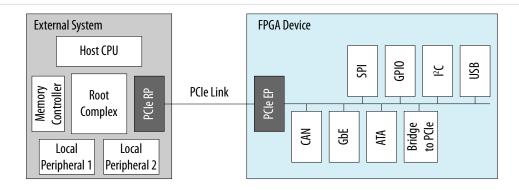
PCIe Gen1, Gen2, and Gen 3 Hard IP

Arria V devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen3, Gen 2, and Gen 1 end point and root port for up to x8 lane configuration.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 8: PCIe Multifunction for Arria V Devices



The Arria V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Arria V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Arria V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Arria V devices.

Hard and Soft Memory Controllers

Arria V GX,GT, SX, and ST devices support up to four hard memory controllers for DDR3 and DDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Arria V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Arria V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices, QDR II+, QDR II, and DDR II+ SRAM devices, and RLDRAM II devices for maximum flexibility.

Note: DDR3 SDRAM leveling is supported only in Arria V GZ devices.



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External Memory Performance

Table 18: External Memory Interface Performance in Arria V Devices

Interface	Voltage	Hard Controller (MHz)	Soft Controller (MHz)			
interrace	(V)	Arria V GX, GT, SX, and ST	Arria V GX, GT, SX, and ST	Arria V GZ		
DDR3 SDRAM	1.5	533	667	800		
DDR3 3DRAM	1.35	533	600	800		
DDR2 SDRAM	1.8	400	400	400		
LPDDR2 SDRAM	1.2	_	400	_		
RLDRAM 3	1.2	_	_	667		
RLDRAM II	1.8	_	400	533		
KLDKAWI II	1.5	_	400	533		
QDR II+ SRAM	1.8	_	400	500		
QDR II+ SIMM	1.5	_	400	500		
QDR II SRAM	1.8	_	400	333		
QDK II SKAM	1.5	_	400	333		
DDR II+	1.8	_	400	_		
SRAM ⁽¹²⁾	1.5	_	400	_		

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 19: HPS External Memory Interface Performance

The hard processor system (HPS) is available in Arria V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	533
	1.35	533
LPDDR2 SDRAM	1.2	333



⁽¹²⁾ Not available as Altera® IP.

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Arria V devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at less than 170 mW
- 10 Gbps transceivers at less than 165 mW
- 6 Gbps transceivers at less than 105 mW

Arria V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left and right outer edges of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

The following figures are graphical representations of a top view of the silicon die, which corresponds to a reverse view for flip chip packages. Different Arria V devices may have different floorplans than the ones shown in the figures.



PCS Support ⁽¹³⁾	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
PCIe Gen1 (x1, x2, x4, x8) PCIe Gen2 ⁽¹⁴⁾ (x1, x2, x4)	2.5 and 5.0	 Phase compensation FIFO Byte serializer 8B/10B encoder PIPE 2.0 interface to the core logic 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO PIPE 2.0 interface to the core logic
GbE	1.25	Phase compensation FIFOByte serializer8B/10B encoder	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO
XAUI ⁽¹⁵⁾	3.125	 Phase compensation FIFO Byte serializer 8B/10B encoder XAUI state machine for bonding four channels 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO XAUI state machine for realigning four channels Deskew FIFO circuitry
SDI	0.27 ⁽¹⁶⁾ , 1.485, 2.97	Phase compensation FIFO Byte serializer	Byte deserializerPhase compensation FIFO
GPON ⁽¹⁷⁾	1.25 and 2.5	byte serializer	1 mase compensation in O
CPRI ⁽¹⁸⁾	0.6144 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder TX deterministic latency 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO RX deterministic latency



⁽¹³⁾ Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.

PCIe Gen2 is supported only through the PCIe hard IP.

⁽¹⁵⁾ XAUI is supported through the soft PCS.

⁽¹⁶⁾ The 0.27 Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

 $^{^{\}left(17\right) }$ The GPON standard does not support burst mode.

⁽¹⁸⁾ CPRI data rates above 6.5536 Gbps, such as 9.8304 Gbps, are supported through the soft PCS.

SoC with HPS

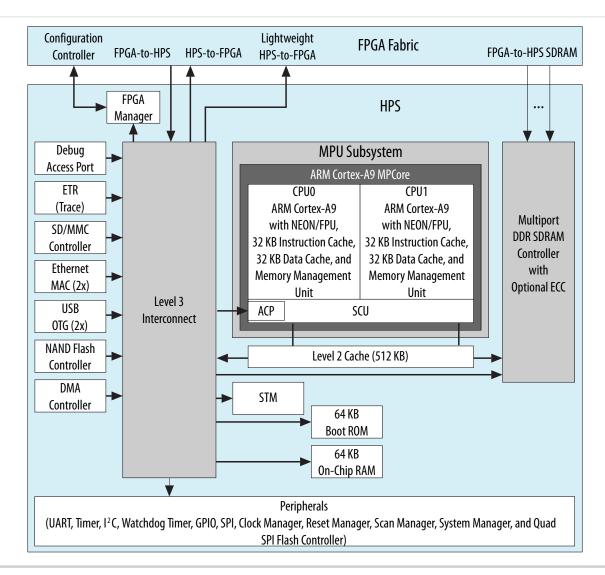
Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

Figure 12: HPS with Dual-Core ARM Cortex-A9 MPCore Processor





Mode	Data Width	Max Clock Rate (MHz)	Max Data I Rate (Mbps)	Decompression	Design Security F	Partial econfiguratio (20)	Remote System Update
	8 bits	125	_	Yes	Yes	_	
FPP	16 bits	125	_	Yes	Yes	Yes ⁽²¹⁾	Parallel flash loader
	32 bits ⁽²²⁾	100	_	Yes	Yes	_	
CvP (PCIe)	x1, x2, x4, and x8 lanes	_	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	_	_	_	_
Configuration	16 bits	125	_	Yes	Yes	Yes (21)	Parallel flash loader
via HPS	32 bits	100	_	Yes	Yes	_	rafanei nasn loadei

Instead of using an external flash or ROM, you can configure the Arria V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Arria V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Note: Although Arria V GZ devices support PCIe Gen3, you can use only PCIe Gen1 and PCIe Gen2 for CvP configuration scheme.

Related Information

Configuration via Protocol (CvP) Implementation in Altera FPGAs User Guide Provides more information about CvP.

Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Arria V devices consume less power than previous generation Arria V FPGAs:

- Total device core power consumption—less by up to 50%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Arria V devices contain several hard IP blocks, including PCIe Gen1, Gen2, and Gen3, GbE, SRIO, GPON, and CPRI protocols, that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.



⁽²⁰⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

⁽²¹⁾ Supported at a maximum clock rate of 62.5 MHz.

⁽²²⁾ Arria V GZ only

Date	Version	Changes
July 2012	2.1	 Added –I3 speed grade to Figure 1 for Arria V GX devices. Updated the 6-Gbps transceiver speed from 6.553 Gbps to 6.5536 Gbps in Figure 3 and Figure 1.
June 2012	2.0	 Restructured the document. Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. Added Table 1, Table 3, Table 12, Table 15, and Table 16. Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 13, Table 14, and Table 19. Updated Figure 1, Figure 2, Figure 3, Figure 4, and Figure 8. Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. Text edits throughout the document.
February 2012	1.3	 Updated Table 1–7 and Table 1–8. Updated Figure 1–9 and Figure 1–10. Minor text edits.
December 2011	1.2	Minor text edits.
November 2011	1.1	 Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–6, Table 1–7, Table 1–9, and Table 1–10. Added "SoC FPGA with HPS" section. Updated "Clock Networks and PLL Clock Sources" and "Ordering Information" sections. Updated Figure 1–5. Added Figure 1–6. Minor text edits.
August 2011	1.0	Initial release.

